

N-Channel 60-V (D-S) MOSFET

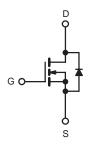
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A)		
60	0.030 at V _{GS} = 10 V	8.0		
	0.036 at V _{GS} = 4.5 V	6.5		

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFETs
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unles	ss otherwise r	noted		
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	60		V
Gate-Source Voltage		V_{GS}	± 20		
Continuous Drain Current (T _{.I} = 175 °C) ^a	T _A = 25 °C	I _D	8.0	7.0	
Continuous Diain Current (1) = 175 C)	T _A = 70 °C		6.4	5.6	Α
Pulsed Drain Current		I _{DM}	40		A
Avalanche Current		I _{AS}	15		
Single Pulse Avalanche Energy		E _{AS}	11		mJ
Manianum Danian Disainational	T _A = 25 °C	- P _D	3.3	1.7	W
Maximum Power Dissipation ^a	T _A = 70 °C		2.3	1.2	VV
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Mariana la sation to Ambient 3	t ≤ 10 s	- R _{thJA}	36	45	°C/W
Maximum Junction-to-Ambient ^a	Steady State		75	90	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	17	20	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.



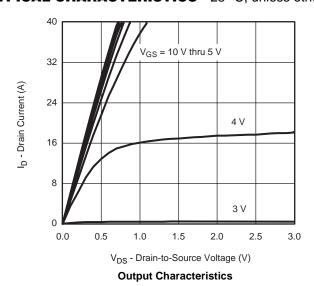
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				•			
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$				V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		3	V	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zana Oata Waltana Busin Oamani	I _{DSS}	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA	
Zero Gate Voltage Drain Current		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			20		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	40			Α	
		$V_{GS} = 10 \text{ V}, I_D = 6.0 \text{ A}$		0.030			
	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 6.0 \text{ A}, T_J = 125 \text{ °C}$		0.035		Ω	
Drain-Source On-State Resistance ^a		$V_{GS} = 10 \text{ V}, I_D = 6.0 \text{ A}, T_J = 175 ^{\circ}\text{C}$		0.040			
		$V_{GS} = 4.5 \text{ V}, I_D = 5.1 \text{ A}$		0.036			
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 6.0 \text{ A}$		25		S	
Diode Forward Voltage ^a	V_{SD}	I _S = 1.7 A, V _{GS} = 0 V		0.8	1.2	V	
Dynamic ^b				•			
Total Gate Charge	Q_g			18	27		
Gate-Source Charge	Q_{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 6.0 \text{ A}$		3.4		nC	
Gate-Drain Charge	Q_{gd}			5.3			
Gate Resistance	R_g	$V_{GS} = 0.1 \text{ V}, f = 5 \text{ MHz}$	0.5	1.4	2.4	Ω	
Turn-On Delay Time	t _{d(on)}			10	20		
Rise Time	t _r	$V_{DD} = 30 \text{ V}, R_L = 30 \Omega$		10	20		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 1 A, V_{GEN} = 10 V, R_g = 6 Ω		25	50	ns	
Fall Time	t _f			12	24		
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 1.7 A, dl/dt = 100 A/μs		50	80		

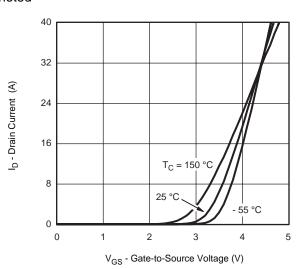
Notes:

- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

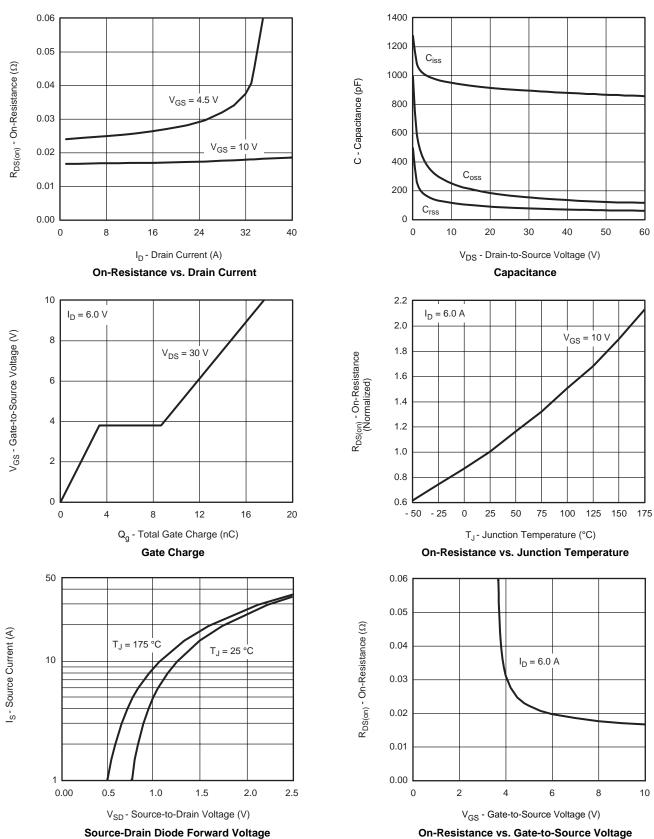




Transfer Characteristics

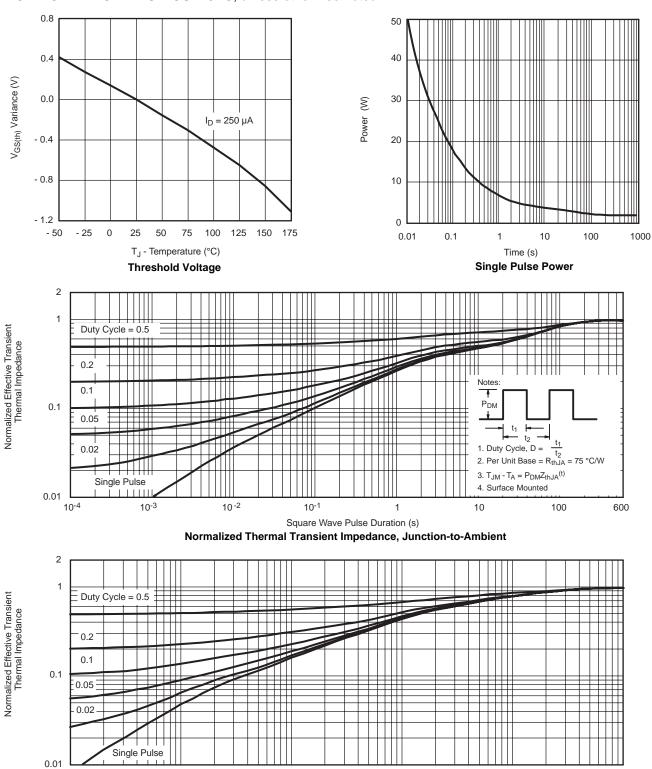


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Square Wave Pulse Duration (s)

Normalized Thermal Transient Impedance, Junction-to-Foot

10

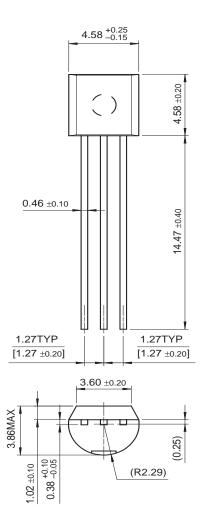
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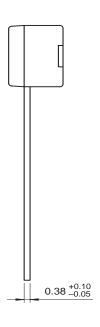
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Mechanical Dimensions

TO-92







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